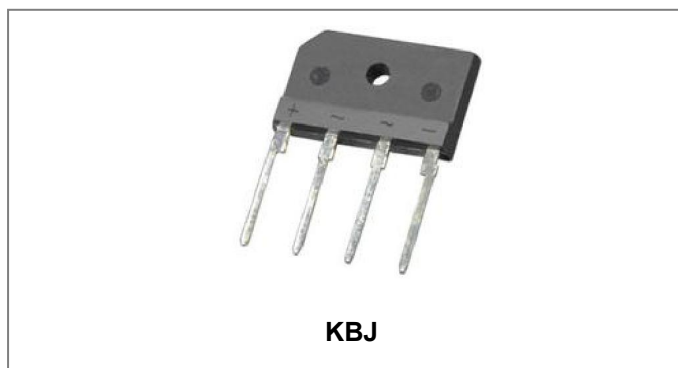


KBJ1010G-A

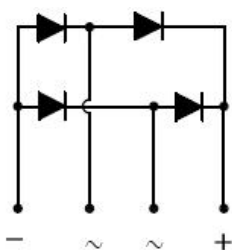
GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER



Features

- Glass passivated chip junction KBJ
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low forward voltage drop
- Low reverse leakage current
- High surge current capability
- “-A” is an AEC-Q101 qualified device
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: Molded plastic, KBJ
- Epoxy: UL 94V-0 rate flame retardant
- Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed
- Mounting position: Any
- Weight: 0.16ounce, 4.6gram

Maximum Ratings: @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Type Number	Symbol	KBJ1010G-A	Units
Marking Code		KBJ1010G	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	1000	V
RMS Reverse Voltage	V_{RMS}	700	V
Average forward rectified output current @T _C =80°C	I_o	10	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	150	A
I ² t Rating for fusing (t <8.3ms)	I ² t	93	A ² s

Electrical Characteristics: @T_A=25°C unless otherwise specified

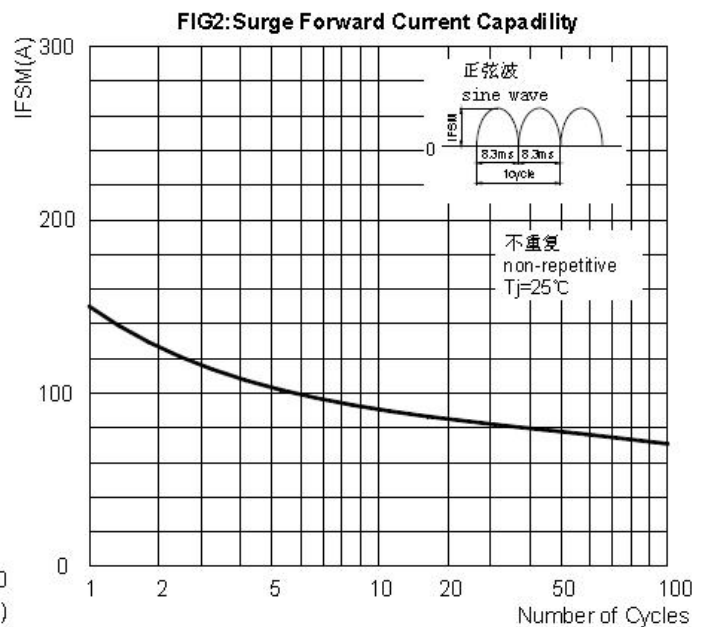
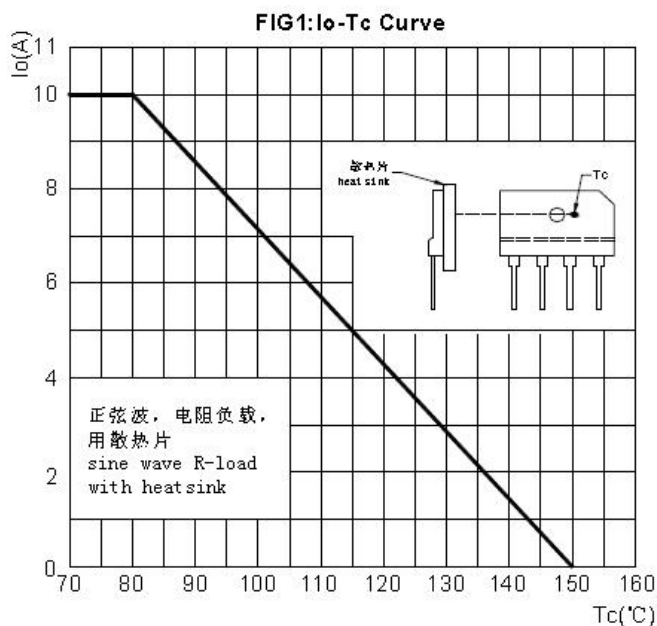
Type Number	Symbol	KBJ1010G-A	Units
Forward Voltage (per element)* @I _F =5A	V _F	1.1	V
Peak Reverse Current* @T _A = 25°C At Rated DC Blocking Voltage* @T _A = 125°C	I _{RM}	10 500	μA

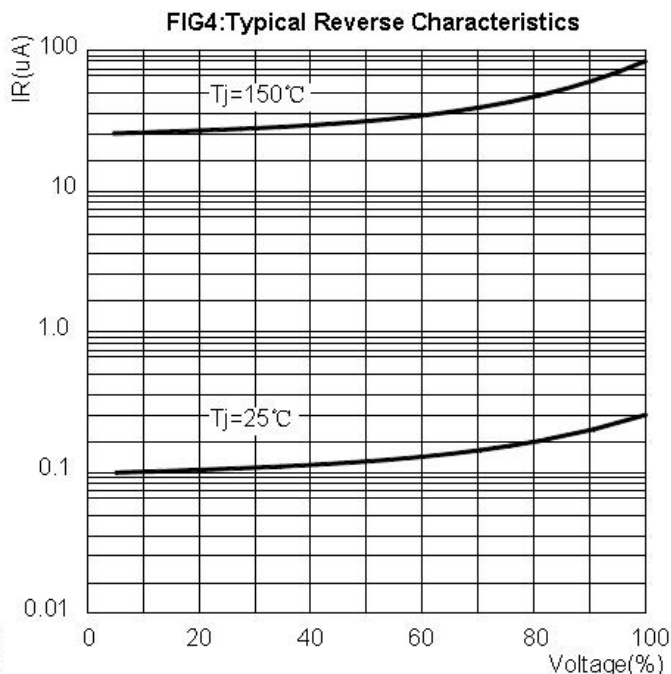
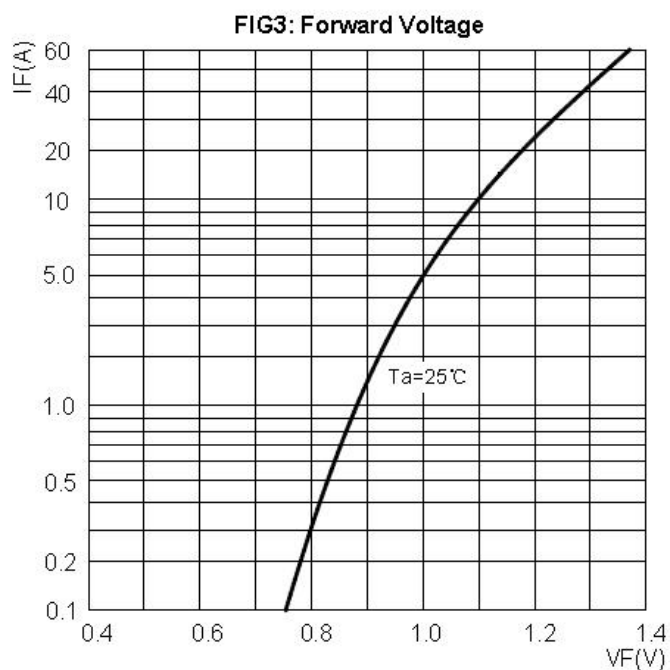
* Pulse width < 300 μs, duty cycle < 2%

Thermal-Mechanical Specifications: @T_A=25°C unless otherwise specified

Type Number	Symbol	KBJ1010G-A	Units
Typical Thermal Resistance(Note 1)	R _{θJC}	2.3	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Note: 1. Between junction and case, with heatsink

Ratings and Characteristics Curves


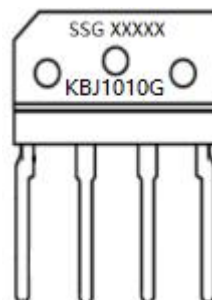


Ordering Information

Device	Package	Plating	Shipping
KBJ1010G-A	KBJ (Pb-Free)	Pure Sn	250pcs / box

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

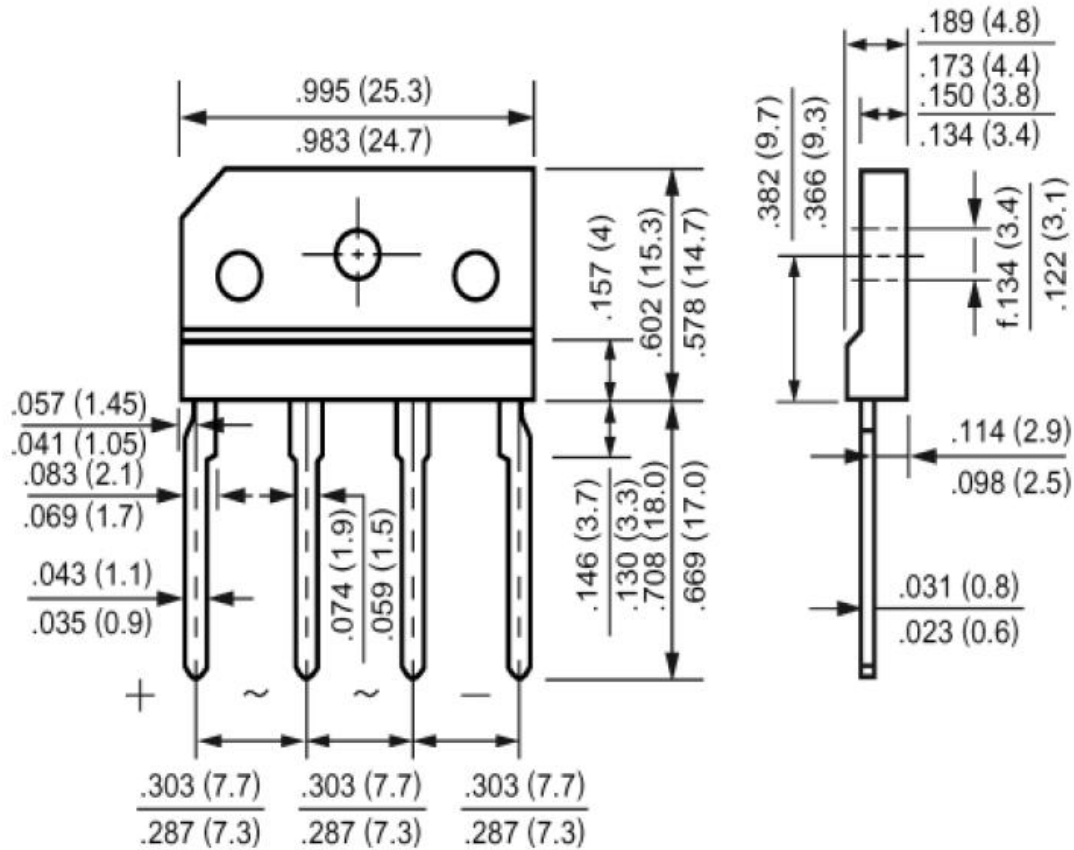


Where XXXXX is YYWWL

SSG = SSG
 YY = Year
 WW = Week
 L = Lot Number
 KBJ1010G = Marking code

Cautions: Molding resin
 Epoxy resin UL:94V-0

Mechanical Dimensions KBJ (Inches/Millimeters)





DISCLAIMER:

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- 2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.
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